

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1319	174/254.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 04:40
L2	49	"4814855"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 04:43
L3	2	("4814855").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 04:43
L4	2	("5859471").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 04:44
L5	147	("4707724" "5311056").PN. OR ("5859471").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 04:46
L6	21	"5357400"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 04:50
L7	2	("5357400").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 04:50
L8	2	("6992372").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 04:51
L9	3	("6320135").PN. OR ("6992372").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 04:52
L10	1	"10519144"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 05:02
L11	12	"6320135"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 05:07
L12	2	("6320135").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 05:08

L13	2	("20050056915").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 05:19
L14	1	("2005/0056915").URPN.	USPAT	OR	ON	2008/12/05 05:20
L15	6	("20050056915" "20050121779" "20050186702" "20050194693" "20060103027" "6992372"). PN. OR ("7282389").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 05:20
L16	6	"6,262,473"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:23
L17	2	("6,262,473").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 06:23
L18	1	("6320135").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:32
L19	7	("4177519" "5338973" "5585675" "5820952" "5996768" "6180215" "6201194").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:33
L20	1315	174/250.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:33
L21	5	20 and dummy adj wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:34
L22	18	sprocket adj holes and dummy adj wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:35
L23	2	20 and 22	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:35
L25	1	"20040004823"	USPAT	OR	ON	2008/12/05 06:38
L26	13	"6572780"	USPAT	OR	ON	2008/12/05 06:42
L27	2	("6572780").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 06:42
L28	21	sprocket adj holes and dummy near2 wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:44
L29	5369	sprocket adj holes	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:44
L30	589	dummy adj wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:45
L31	18	29 and 30	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:45

L32	2	("20010045651" "20030020163").PN. OR ("6958288").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:48
L33	1	"20040238968"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:51
L34	2	"20040004823"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 07:28
L36	310	sprocket adj holes and concave	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:24
L37	194322	("printed circuit board" or "PCB")	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:25
L38	12	36 and 37	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:25
L39	1003	361/749.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:41
L40	2	39 and sprocket adj holes and dummy adj wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:43
S2	2546	housing with gap and shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:00
S6	58	S2 and burst	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:02
S7	31	S2 and burst and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:02
S8	42	S2 and TVS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:02
S9	4	S7 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:02
S10	2386	ELECTRONIC adj DEVICE and ESD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:04
S11	3	S10 and burst same TVS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:05

S12	776762	electronic adj device and joint or layer and circuit adj board and IC or integrated adj circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:41
S13	22312	S12 and ground and housing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:43
S14	3108	S13 and shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:43
S15	88	S14 and 361/818.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:43
S16	11	S15 and capacitor and ESD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:44
S17	2386	electronic adj device and ESD and electronic adj device	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:51
S20	772	361/88.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 17:06
S21	1991	361/818.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 17:06
S22	1	S21 and housing adj seam and IC	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 17:07
S28	66	S21 and housing and IC	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 17:09
S30	85511	housing and gap and shielding adj unitground burst	USPAT	OR	ON	2008/04/07 17:53

S31	2	housing and gap and shielding adj unit and ground and burst	USPAT	OR	ON	2008/04/07 17:53
S32	13	("3073916" "3670299" "4115667" "4187502").PN. OR ("5012457").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/07 17:54
S33	154	shield\$4 same esd same (printed pcb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:20
S34	92	S33 same ground\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:20
S35	21	S34 same (opening aperture hole window)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:22
S36	33	S33 same (opening aperture hole window)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:23
S37	21	S36 and S35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:24
S38	1052	361/212.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:29
S40	3	S33 and S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:30
S41	29	S34 same (opening aperture hole window gap)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 13:27
S42	2	"20060023387"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 13:36

S43	2	"20060012969"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 13:38
S44	5086	antiFuse	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 14:24
S48	2	"20060172573"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:36
S51	9	notebook and housing and ESd and filter and shielding and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:45
S52	1919339	electronic adj device and ESD and housing and gap and shielding and component filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:55
S53	39	electronic adj device and ESD and housing and gap and shielding and component and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:55
S55	13877	housing and gap and shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:17
S56	5196	S55 and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:17
S57	5196	S56 and shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:18
S58	228	S57 and TVS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:19
S59	33	(shield\$4 same esd same (printed pcb) same (opening aperture hole window))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:40

S60	558764	"33" and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:40
S61	1	S59 and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:40
S62	17	"4801273"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 10:37
S63	2	("4801273").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/09 10:37
S64	1002418	nootbook and housing and ESd and filter and shielding and ground and gap window	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 13:36
S65	2388	ELECTRONI C adj DEVICE and ESD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 14:34
S66	41	S65 and PDA and notebook and mobile adj phone	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 14:39
S67	2	"20020048156"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 19:08
S69	2	"20050009381"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 19:15
S70	3	2004/0183209	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:18
S72	2	("20040183209").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/10 09:18

S74	17	built near in near capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:26
S76	13	built near in near capacitor and power	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:26
S77	9	S76 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:34
S78	9	S77 and power	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:36
S79	697	APPARATUS and INTERCONNECTING and BALL adj GRID adj ARRAY and PRINTED adj CIRCUIT adj BOARD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:55
S80	0	S79 and power adj bar	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:57
S81	82	S79 and bar	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:57
S82	11	S81 and power adj supply	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:57
S83	1543	361/816.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 13:58
S84	669	361/800.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:04
S85	875	361/803.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:04

S86	9	S83 and S84 and S85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:04
S87	199405	@ad<="20040415" and ("PCB" or "printed circuit board") with shield and ground adj layer and electromagnetic adj radiation and via metal adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:11
S88	2068	S87 and polymer adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:13
S90	29	S88 and flange and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:13
S91	486	174/377.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:16
S92	4	S88 and S91	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:16
S93	2225371	S90 and mechanical adj connector and ground adj plane and via or window or aperture	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:18
S94	7	S90 and mechanical adj connector and ground adj plane and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:18
S95	3	S90 and mechanical adj connector and ground adj plane and via and metallized adj polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:19
S96	3	"20060094296"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 16:23

S97	9	"6712544"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 16:30
S98	3	("6712544").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/10 16:31
S99	20	("2447299" "3316798" "3413886" "3468091" "4367053" "5288191" "5419650" "5895189" "6071036" "6487882").PN. OR ("6712544").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/10 16:35
S100	14110	@ad<="20050429" and ("PCB" or "printed circuit board" or substrate) with chip same pad and ground adj layer and insulativeand passive and grooves	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 18:13
S101	30	174/661.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 18:13
S102	175	"5353498"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:27
S103	2	("5353498").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/11 09:28
S104	54	packaging adj substrate and array and chip adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:38
S105	54	S104 and chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:39
S106	6925353	S105 and via window open\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:39

S107	36	S105 and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:40
S109	1	S104 and overflow near preventive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:41
S111	14040	chip near pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:42
S112	54	packaging adj substrate and array and chip adj pad and S111	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:42
S113	77	packaging adj substrate and chip adj pad and S111	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:42
S114	2	S113 and overflow near preventive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:42
S115	2	"overflow-preventive grooves "	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:53
S116	4	"overflow-preventive"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:55
S117	48	"2763403"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:56
S119	118	packaging adj substrate and chip near pad	USPAT	OR	ON	2008/04/11 10:01
S120	311451	packaging adj substrate and chip near pad and overflownear grooves	USPAT	OR	ON	2008/04/11 10:01
S124	8	packaging adj substrate and chip near pad and grooves	USPAT	OR	ON	2008/04/11 10:02

S125	4	"overflow-preventive"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:04
S126	198522	"overflow"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:04
S127	1	S104 and S126	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:05
S128	50	S126 and array and chip adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:05
S129	5	S128 and grooves	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:06
S130	272	@ad<="20040924" and ("PCB" or "printed circuit board") with insulating adj substrate and capacitor and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:34
S131	85	S130 and conductive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:35
S132	9758	S131 conductive adj circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:36
S134	1	S131 and conductive near circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:36
S135	64	@ad<="20040924" and ("PCB" or "printed circuit board") with insulating adj substrate and capacitor and insulating adj substrate and resistors and capacitors and conductive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:53

S136	52	S135 and integrated adj circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:54
S137	21	S136 and electrodes and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:54
S138	8	"6,948,940"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/14 10:31
S139	2	("6,948,940").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/14 10:31
S140	2	("11116066").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/14 10:48
S141	3	"11116066"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/14 10:49
S142	8	"6948940"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/14 11:10
S143	2	("6948940").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/14 11:10
S144	1317	174/254.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 10:48
S145	7	"6,262,473"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 10:49
S146	2	("6,262,473").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/01 10:50

S147	2	("20030107120").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/01 14:24
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